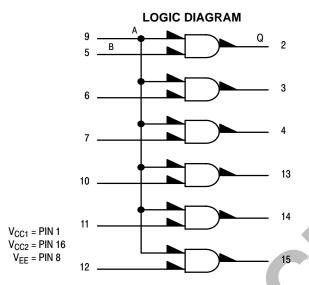
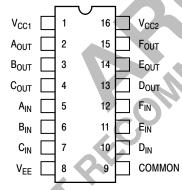
Hex AND Gate

The MC10197 provides a high speed hex AND function with strobe capability.

- $P_D = 200 \text{ mW typ/pkg (No Load)}$
- $t_{pd} = 2.8 \text{ ns typ (B-Q)}$
- $t_{pd} = 3.8 \text{ ns typ (A-Q)}$
- t_r , $t_f = 2.5$ ns typ (20%–80%)



DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

TRUTH TABLE

Inp	uts	Output		
Α	В	Q		
L L		L		
L	Н	L		
Н	L	L		
Н	Н	Н		



ON Semiconductor

http://onsemi.com





CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping		
MC10197L	CDIP-16	25 Units / Rail		
MC10197P	PDIP-16	25 Units / Rail		
MC10197FN	PLCC-20	46 Units / Rail		

ELECTRICAL CHARACTERISTICS

						7	Test Limits	<u> </u>			
			Pin Under	-30)°C		+25°C		+85	5°C	
Characteristi	Characteristic		Test	Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply Drain	Current	Ι _Ε	8		54		39	49		54	mAdc
Input Current		I _{inH}	5 9		425 460			265 290		265 290	μAdc
		I _{inL}	5	0.5		0.5		0.3			μAdc
Output Voltage	Logic 1	V _{OH}	2	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700	Vdc
Output Voltage	Logic 0	V _{OL}	2	-1.890	-1.675	-1.850		-1.650	-1.825	-1.615	Vdc
Threshold Voltage	Logic 1	V _{OHA}	2	-1.080		-0.980			-0.910		Vdc
Threshold Voltage	Logic 0	V _{OLA}	2		-1.655			-1.630		-1.595	Vdc
Switching Times (50	Ω Load)									C	ns
Propagation Delay		t ₅₊₂₊ t ₉₊₂₊	2 2	1.1 1.1	4.2 5.3	1.1 1.1	2.8 3.5	4.0 5.0	1.1 1.1	4.4 5.5	
Rise Time (20	to 80%)	t ₂₊	2	1.1	4.7	1.1	2.5	4.5	1.1	5.0	
Fall Time (20	to 80%)	t ₂₋	2	1.1	4.7	1.1	2.5	4.5	1.1	5.0	

ELECTRICAL CHARACTERISTICS (continued)

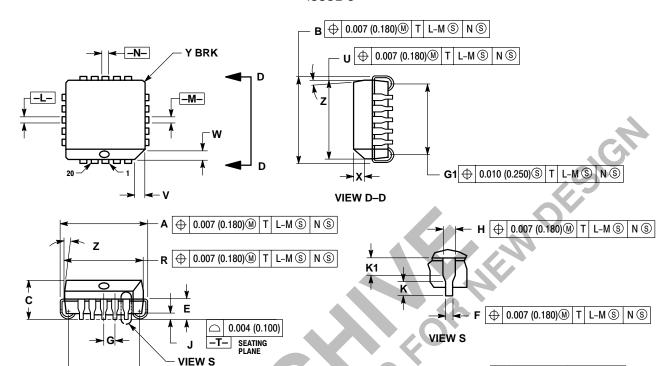
	ACTEMBLE	(00)1111100	, a,						
		TEST VOLTAGE VALUES (Volts)							
	V _{IHmax}	V _{ILmin}	V_{IHAmin}	V _{ILAmax}	V _{EE}				
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
			Pin	TEST V	OLTAGE AP	PLIED TO P	INS LISTED I	BELOW	
Characteri	stic	Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	(V _{CC}) Gnd
Power Supply Drain C	urrent	ΙE	8					8	1, 16
Input Current	(l _{inH}	5 9	5 9				8 8	1, 16 1, 16
		l _{inL}	5		5			8	1, 16
Output Voltage	Logic 1	V _{OH}	2	5, 9				8	1, 16
Output Voltage	Logic 0	V _{OL}	2					8	1, 16
Threshold Voltage	Logic 1	V _{OHA}	2	9		5		8	1, 16
Threshold Voltage	Logic 0	V_{OLA}	2	9			5	8	1, 16
Switching Times	(50 Ω Load)				+1.11V	Pulse In	Pulse Out	−3.2 V	+2.0 V
Propagation Delay	,O'	t ₅₊₂₊ t ₉₊₂₊	2 2		9 5	5 9	2 2	8 8	1, 16 1, 16
Rise Time	(20 to 80%)	t ₂₊	2		9	5	2	8	1, 16
Fall Time	(20 to 80%)	t ₂₋	2		9	5	2	8	1, 16

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF MICE. NOT PERSON

- OTES:

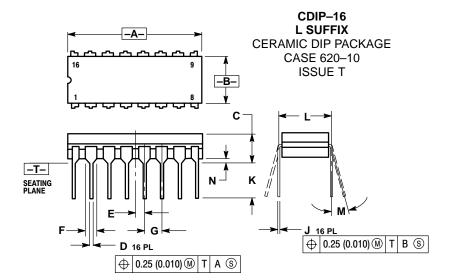
 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 4. DIMENSIONING AND TOLERANCING PER ANSI V14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300).
- DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	



NOTES:

- ANIES.

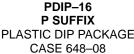
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

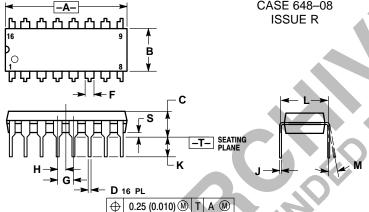
 CONTROLLING DIMENSION: INCH.

 DIMENSION L TO CENTER OF LEAD WHEN

- FORMED PARALLEL.
 DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
E	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54	BSC	
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62	BSC 4	
М	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	





- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS				
DIM	MIN	MAX	MIN	MAX				
Α	0.740	0.770	18.80	19.55				
В	0.250	0.270	6.35	6.85				
С	0.145	0.175	3.69	4.44				
D	0.015	0.021	0.39	0.53				
F	0.040	0.040 0.70		1.77				
G	0.100	BSC	2.54 BSC					
Н	0.050	BSC	1.27 BSC					
J	0.008	0.015	0.21	0.38				
K	0.110	0.130	2.80	3.30				
L	0.295	0.305	7.50	7.74				
M	0° 10°		0 °	10 °				
S	0.020 0.040		0.51	1.01				

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